

MR1083-507
Serial Number: 1071-5550
Reply to Official Action dated 5 April 2004

III. Please replace the original ABSTRACT, Page 9, with the following amended ABSTRACT:

ABSTRACT OF THE DISCLOSURE

~~At oxygen removing process for copper interconnect grown by electrochemical displacement deposition is to remove the oxygen in the reaction solution before displacement and deposition a copper film/conducting wire such that the copper film/conducting wire is grown and has a lower electrode resistance.~~

A solvent, such as deionized water, is heated up to boil to remove the oxygen dissolved in the water before preparing the plating solutions for the growth of copper interconnects. The resistance of the copper grown from the EDD solutions having undergone the oxygen removing process is greatly improved, down to a value very close to copper's ideal value.